

# UTAC Unveils Broadband, Mobile/Wireless Strategy

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Focused resources on enhanced capabilities and total solutions to the fast-growing BM/W segment

Singapore, April 22, 2002 - United Test and Assembly Center Limited ("UTAC") today unveiled its Broadband, Mobile/Wireless (BM/W) strategy, a company-wide focus and initiative to further enhance its capability and service offerings in this segment.

"The BM/W segment represents the fastest growing segment with compound growth rates of about 30% and involves knowledge-intensive and sophisticated capabilities that we believe UTAC is well-placed to provide", said JC Lee, President & CEO of UTAC. " We believe that by focusing our resources in this key area, we will be able to better meet BM/W customer requirements and hence capture leadership position in this space."

UTAC's BM/W strategy will entail further investments in chip-scale packaging, multi-chip modules, RF packages, high-speed digital testing, mixed-signal testing, RF testing, among others. In addition to investing in new assembly and testing capabilities, UTAC is growing its value-added service teams in both package design & development and test engineering to better support its customers. These design, development and engineering centers will also be replicated in the regional markets such as North America and Europe to enable closer support to customers.

Mr Lee added, "The BM/W strategy has actually been in place since the third quarter of 2001. We already have several customer and product/service wins as a result of this focus that will be posted in the coming months, and the unveiling of UTAC's focus on this sector will help put those announcements in context."

The BM/W strategy will both encompass and complement UTAC's existing leadership in memory products. Already, UTAC is the leader in packaging and testing chip-scale memory packages meant for mobile devices.

## About United Test and Assembly Center Ltd (UTAC)

United Test and Assembly Center Ltd. (UTAC), founded on 16th March 1998, is a QS9000/ISO9001/SAC certified semiconductor assembly and test services provider. We offer full turnkey services from wafer sort / laser repair, packaging, Test / Burn in, Mark-Scan-Pack and drop shipment services. In addition, we provide customers with value-added services in package design and simulation, test program development and device characterization, failure analysis services and full reliability test services.

UTAC is committed to provide customers one-stop turnkey semiconductor assembly and testing services for wide spectrum of memory, logic and mixed signal devices.

UTAC World Wide Web address is <http://www.utac.com.sg/>.